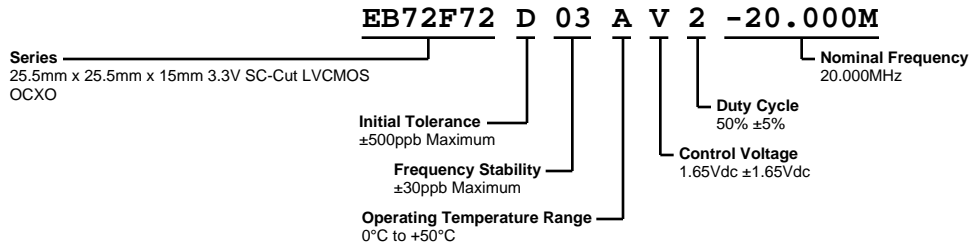


EB72F72D03AV2-20.000M



ELECTRICAL SPECIFICATIONS

| | |
|--|--|
| Nominal Frequency | 20.000MHz |
| Initial Tolerance | ±500ppb Maximum (Measured at nominal Vdd and Vc) |
| Frequency Stability | ±30ppb Maximum |
| Frequency Stability vs. Input Voltage | ±20ppb Maximum (Vdd ±5%) |
| Frequency Stability vs. Load | ±20ppb Maximum (Vload ±5%) |
| Frequency Stability vs. Aging (10 Years) | ±500ppb Maximum (after 72 hours of operation) |
| Frequency Stability vs. Aging (1 Day) | ±2.0ppb Maximum (after 72 hours of operation) |
| Frequency Stability vs. Aging (1 Year) | ±100ppb Maximum (after 72 hours of operation) |
| Operating Temperature Range | 0°C to +50°C |
| Supply Voltage | 3.3Vdc ±5% |
| Warm Up Time | 3 Minutes Maximum (to ±50ppb of final frequency at 1 hour at 25°C) |
| Power Consumption | 1.2Watts Maximum at Steady State at 25°C, 3.6Watts Maximum during Warm Up |
| Output Voltage Logic High (Voh) | 2.6Vdc Minimum (IOH=-4mA) |
| Output Voltage Logic Low (Vol) | 0.4Vdc Maximum (IOL=+4mA) |
| Rise/Fall Time | 6nSec Maximum (Measured at 20% to 80% of waveform) |
| Duty Cycle | 50% ±5% (Measured at 50% of waveform) |
| Load Drive Capability | 15pF Maximum |
| Output Logic Type | CMOS |
| Control Voltage | 1.65Vdc ±1.65Vdc |
| Control Voltage Range | 0.0Vdc to Vdd |
| Frequency Deviation | ±0.5ppm Minimum (Referenced to Fo at Vc=1.65Vdc; Vcc=3.3Vdc) |
| Linearity | ±10% Maximum |
| Reference Voltage Output | 2.8Vdc ±0.2Vdc (Pin 4) |
| Transfer Function | Positive Transfer Characteristic |
| Crystal Cut | SC-Cut |
| Input Impedance | 10kOhms Typical |
| Phase Noise | -90dBc/Hz at 1Hz Offset, -100dBc/Hz at 10Hz Offset, -130dBc/Hz at 100Hz Offset, -145dBc/Hz at 1kHz Offset, -150dBc/Hz at 10kHz Offset (Typical Values) |
| Storage Temperature Range | -55°C to +125°C |

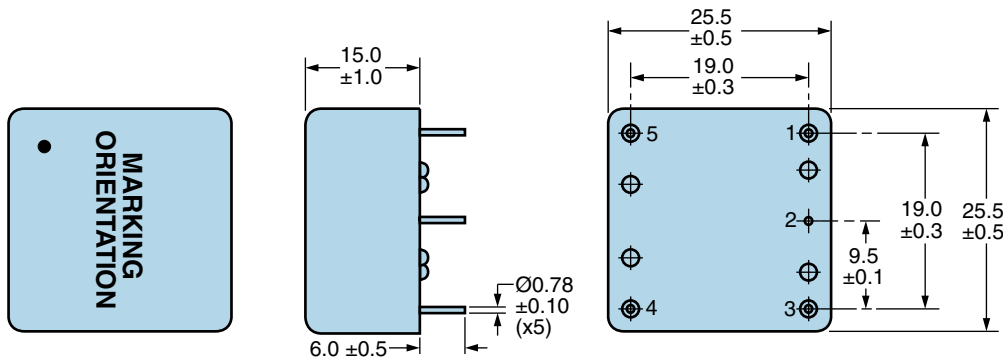
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|------------------------------|---------------------------------------|
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity | MIL-STD-883, Method 2004 |
| Mechanical Shock | MIL-STD-202, Method 213 Condition C |
| Resistance to Soldering Heat | MIL-STD-202, Method 210 |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010 |
| Vibration | MIL-STD-883, Method 2007 Condition A |

EB72F72D03AV2-20.000M



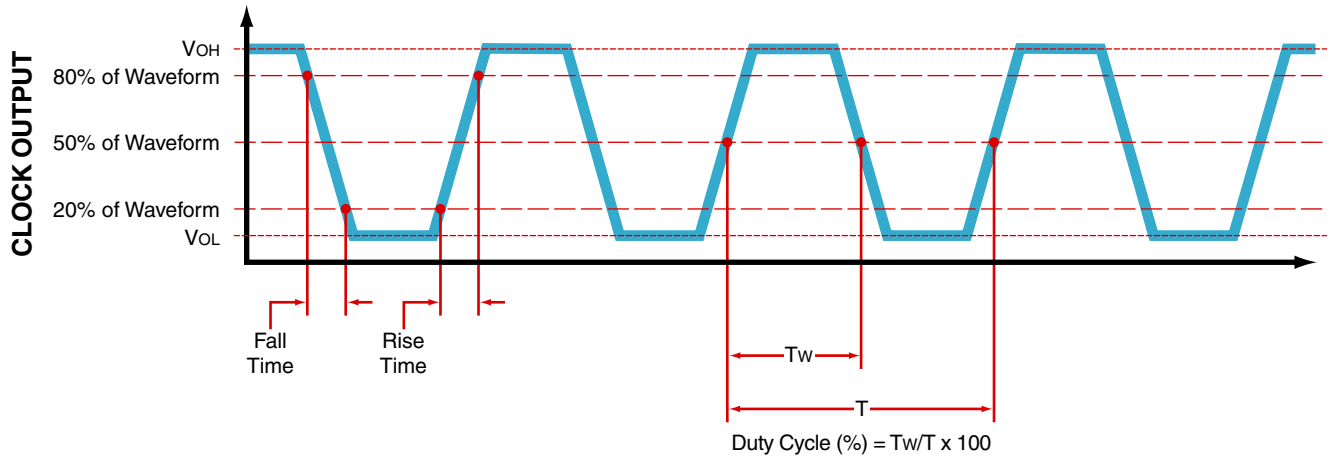
MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION |
|-----|--------------------------|
| 1 | Output |
| 2 | Case/Ground |
| 3 | Voltage Control |
| 4 | Reference Voltage Output |
| 5 | Supply Voltage |

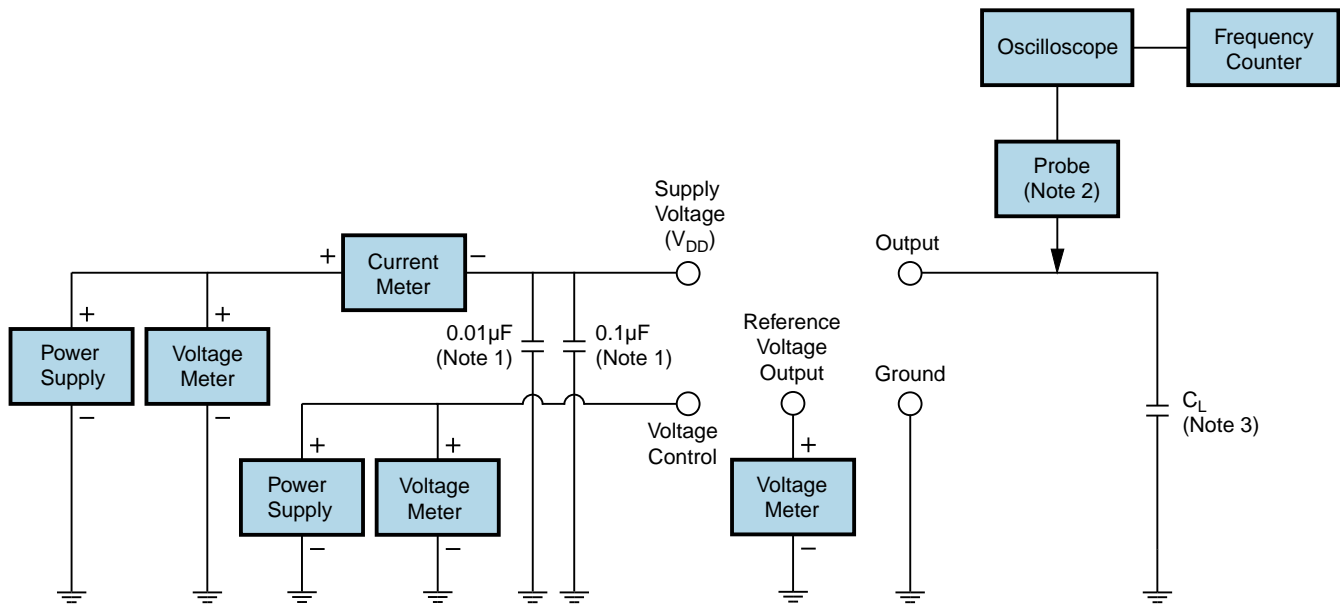
| LINE | MARKING |
|------|---|
| 1 | ECLIPTEK |
| 2 | 20.000M |
| 3 | XXYYZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year |

OUTPUT WAVEFORM



EB72F72D03AV2-20.000M

Test Circuit for Voltage Control Option



Note 1: An external $0.1\mu\text{F}$ low frequency tantalum bypass capacitor in parallel with a $0.01\mu\text{F}$ high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance ($<12\text{pF}$), 10X attenuation factor, high impedance ($>10\text{Mohms}$), and high bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.